FLAGLESS SEMICONDUCTOR DEVICE AND METHOD FOR MAKING THE SAME

Abstract of the Disclosure

A flagless semiconductor device (10) includes a semiconductor die (22) having a plurality of bond pads (26) which are electrically coupled to a plurality of leads (16) by wire bonds (28). The die is supported by two cantilevered tie bars (18). Use of cantilevered tie bars decreases the total plastic-metal interface area in a plastic encapsulated device, thereby lessening the probability of internal delamination and package cracking. The cantilevered tie bars also permit a variety of die sizes to be used with the same lead frame design. Suitable configurations for cantilevered tie bars include, but are not limited to, U-shape, T-shape, and H-shape configurations.

(FIG. 1 accompanies this abstract)